

mSAP

Modified Semi-Additive Process

mSAP is a cost effective process for fine line substrates which allows for a high degree of automation, high yields and lean manufacturing. MacDermid Alpha Electronics Solutions has a portfolio which encompasses every process step.

Copper Reduction

CircuEtch 100

Pattern Plate Via Fill

MacuSpec™ VF-TH

LDD Pretreatment

MultiBond™ 500

Dry Film Stripper

UltraStrip LDI

Post LDD Conversion

CoreClean

Differential Etch

CircuEtch 300

Primary Metallization

System™ Desmear
Shadow® LE, Eclipse™ LE
M-Copper® Series

Innerlayer Adhesion

M-Speed HF

Solder Mask Adhesion

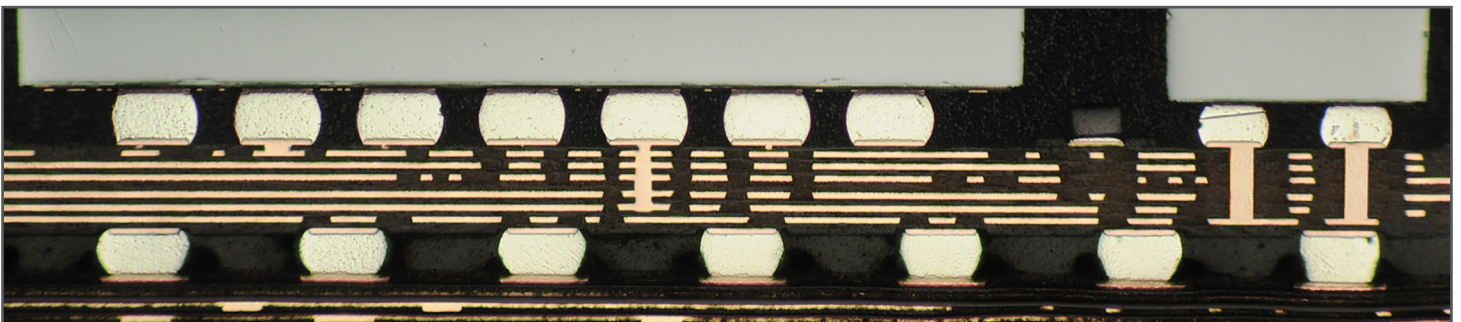
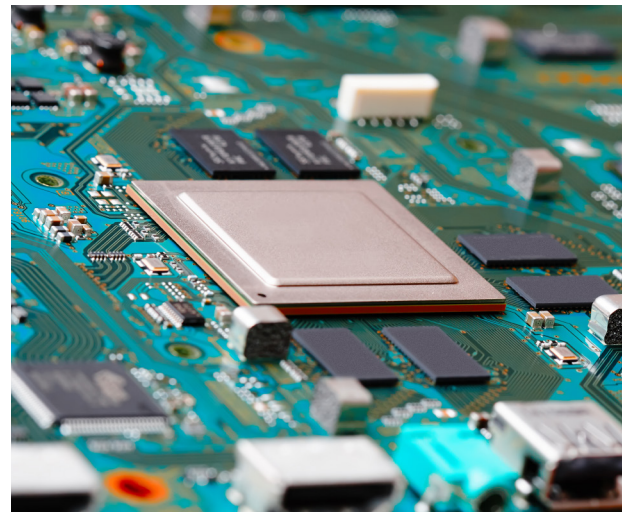
MultiPrep 200

Dry Film Adhesion

MultiPrep 200

Final Finish

ENTEK® PLUS HT
Affinity™ ENIG/ENEPIG



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